

# Is Now Part of



# ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at <a href="https://www.onsemi.com">www.onsemi.com</a>

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



November 2013

# FDN338P

# P-Channel 2.5V Specified PowerTrench<sup>O</sup> MOSFET

## **General Description**

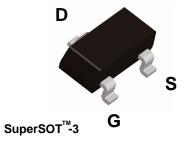
This P-Channel 2.5V specified MOSFET uses Fairchild's advanced low voltage PowerTrench process. It has been optimized for battery power management applications.

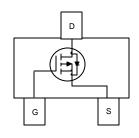
## **Applications**

- Battery management
- Load switch
- Battery protection

## **Features**

- -1.6 A, -20 V.  $R_{DS(ON)} = 115 \text{ m}\Omega$  @  $V_{GS} = -4.5 \text{ V}$  $R_{DS(ON)} = 155 \text{ m}\Omega$  @  $V_{GS} = -2.5 \text{ V}$
- Fast switching speed
- High performance trench technology for extremely low  $R_{\text{DS}(\text{ON})}$
- SuperSOT<sup>TM</sup> -3 provides low R<sub>DS(ON)</sub> and 30% higher power handling capability than SOT23 in the same footprint





# Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V <sub>DSS</sub>	Drain-Source Voltage	-20	V
V <sub>GSS</sub>	Gate-Source Voltage	±8	V
I <sub>D</sub>	Drain Current - Continuous	-1.6	Α
	- Pulsed	-5	
P <sub>D</sub>	Maximum Power Dissipation (Note 1a)	0.5	W
	(Note 1b)	0.46	
$T_J$ , $T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	°C

# **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
R₀JC	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

# Package Marking and Ordering Information

	•	•	_		
	Device Marking	Device	Reel Size	Tape width	Quantity
_	338	FDN338P	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics			I	I	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-20			V
ΔBV <sub>DSS</sub> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, Referenced to 25°C		-16		mV/°C
loss	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V},  V_{GS} = 0 \text{ V}$			-1	μΑ
GSSF	Gate-Body Leakage, Forward	$V_{GS} = 8 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
GSSR	Gate-Body Leakage, Reverse	$V_{GS} = -8 \text{ V},  V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-0.4	-0.8	-1.5	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$ , Referenced to 25°C		2.7		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	$\begin{split} &V_{GS} = -4.5 \text{ V},  I_D = -1.6 \text{ A} \\ &V_{GS} = -2.5 \text{ V},  I_D = -1.3 \text{ A} \\ &V_{GS} = -4.5 \text{ V}, I_D = -1.6 \text{ A}, T_J = 125 ^{\circ}\text{C} \end{split}$		88 117 116	115 155 165	mΩ
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS} = -4.5 \text{ V},  V_{DS} = -5 \text{ V}$	<b>-</b> 5			Α
<b>g</b> FS	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -1.6 \text{ A}$		6		S
Dvnamic	Characteristics			I		
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -10 \text{ V},  V_{GS} = 0 \text{ V},$		451		pF
Coss	Output Capacitance	f = 1.0 MHz		75		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			33		pF
Switchin	g Characteristics (Note 2)			I	I	
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = -10 \text{ V},  I_D = -1 \text{ A},$		10	20	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = -4.5 \text{ V},  R_{GEN} = 6 \Omega$		11	20	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			16	29	ns
t <sub>f</sub>	Turn-Off Fall Time			6.5	13	ns
Qq	Total Gate Charge	$V_{DS} = -10 \text{ V},  I_{D} = -1.6 \text{ A},$		4.4	6.2	nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{GS} = -4.5 \text{ V}$		1.1		nC
Q <sub>gd</sub>	Gate-Drain Charge			0.7		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings		•	•	
ls	Maximum Continuous Drain–Source				-0.42	Α
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V},  I_S = -0.42  \text{(Note 2)}$		-0.7	-1.2	V

### Notes:

<sup>1.</sup>  $R_{\theta,UA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta,UC}$  is guaranteed by design while  $R_{\theta,CA}$  is determined by the user's board design.



a) 250°C/W when mounted on a 0.02 in² pad of 2 oz. copper.

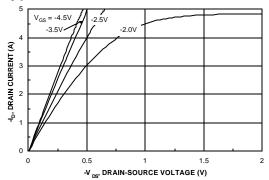


b) 270°C/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%

# **Typical Characteristics**



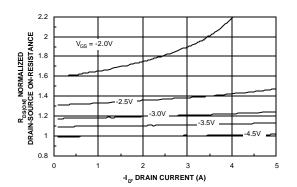
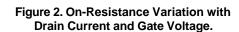
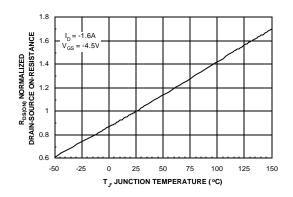


Figure 1. On-Region Characteristics.





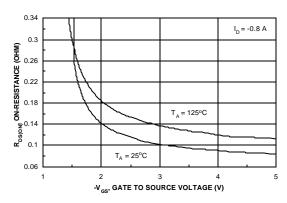
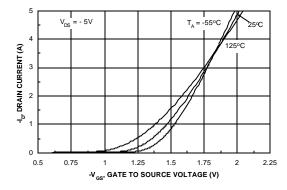


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



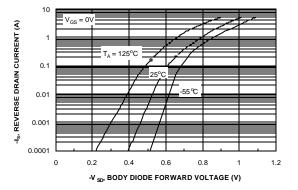
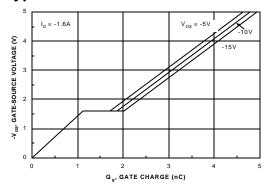


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

# **Typical Characteristics**



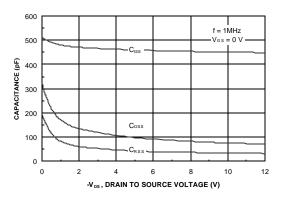
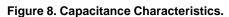
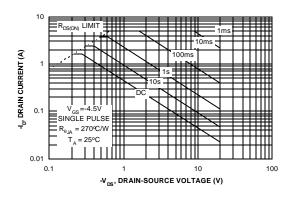


Figure 7. Gate Charge Characteristics.





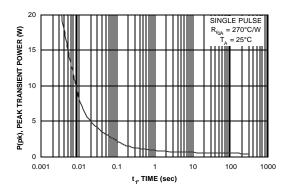


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

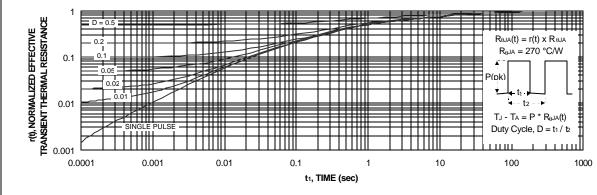


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.





#### **TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

F-PFS™ AccuPower™ FRFET® AX-CAP®\*

BitSiC™ Global Power Resource<sup>SM</sup> Build it Now™ GreenBridge™ CorePLUS™ Green FPS™

Green FPS™ e-Series™ CorePOWER™

CROSSVOLT™ Gmax™ CTL™ GTO™ IntelliMAX™ Current Transfer Logic™ DEUXPEED® ISOPLANAR™

Marking Small Speakers Sound Louder Dual Cool™ EcoSPARK®

and Better™ EfficentMax™ MegaBuck™

MICROCOUPLER™ ESBC™ MicroFET™

MicroPak™ MicroPak2™ MillerDrive™

Fairchild Semiconductor® MotionMax™ FACT Quiet Series™ mWSaver<sup>®</sup> OptoHiT™ OPTOLOGIC® OPTOPLANAR®  $(l)_{\mathbb{R}}$ PowerTrench® PowerXS™

Programmable Active Droop™

OFET QSTM

Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™ SignalWise™

SmartMax™ SMART START™

Solutions for Your Success™

SPM® STEALTH™ SuperFET®

SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS<sup>®</sup> SyncFET™

Sync-Lock™ SYSTEM®\*

GENERAL TinyBoost<sup>®</sup> TinyBuck<sup>®</sup> TinyCalc™ TinyLogic<sup>®</sup> TINYOPTO™ TinyPower™ TinyPWM™ TinyWire™ TranSiC™ TriFault Detect™ TRUECURRENT®\* μSerDes™

UHC<sup>®</sup> Ultra FRFET™ UniFET™ VCX™

VisualMax™ VoltagePlus™ XS™

\*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

Fairchild®

FACT

FAST®

FPSTM

FastvCore™

FETBench™

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE PRINCHILD SEMICONDUCTOR RESERVES THE RIGHT TO IMPROVE CHANGES WITHOUT FOR THE RIGHT ROBUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN. WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY
FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE
EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

### ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

### PRODUCT STATUS DEFINITIONS **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdt/Patent-Marking.pdf">www.onsemi.com/site/pdt/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

## **PUBLICATION ORDERING INFORMATION**

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative